



# 22V, 20A Synchronous Step Down COT Power Module

### **General Description**

The XR79120 is a 20A synchronous step-down Power Module for point-of load supplies. A wide 4.5V to 22V input voltage range allows for single supply operation from industry standard 5V, 12V, and 19.6V rails.

With a proprietary emulated current mode Constant On-Time (COT) control scheme, the XR79120 provides extremely fast line and load transient response using ceramic output capacitors. It requires no loop compensation hence simplifying circuit implementation and reducing overall component count. The control loop also provides 0.12% load and 0.17% line regulation and maintains constant operating frequency. A selectable power saving mode allows the user to operate in discontinuous mode (DCM) at light current loads thereby significantly increasing the converter efficiency. With a 93% peak efficiency and 84% for loads as low as 100mA, the XR79120 is suitable for applications where low power losses are important.

A host of protection features, including over-current, over-temperature, short-circuit and UVLO, help achieve safe operation under abnormal operating conditions.

The XR79120 is available in a RoHS compliant, green/halogen free space-saving 74-pin 12x14x4mm QFN package. With integrated controller, drivers, bootstrap diode and capacitor, MOSFETs, inductor, CIN and COUT, this solution allows the smallest possible 20A POL design.

#### **FEATURES**

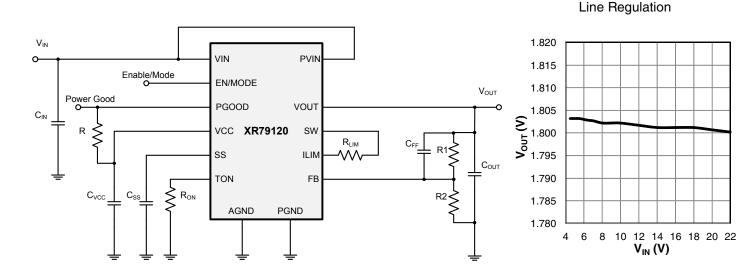
- Controller, drivers, bootstrap diode and capacitor, MOSFETs, Inductor, CIN and COUT integrated in one package
- 20A Step Down Module
  - □ Wide 4.5V to 22V Input Voltage Range
  - □ >0.6V Adjustable Output Voltage
- Proprietary Constant On-Time Control
  - No Loop Compensation Required
  - □ Stable Ceramic Output Capacitor Operation
  - □ Programmable 200ns to 2us On-Time
  - □ Constant 400kHz to 600kHz Frequency
- Selectable CCM or CCM/DCM
  - □ CCM/DCM for high efficiency at light-load
  - □ CCM for constant frequency at light-load
- Programmable Hiccup Current Limit with Thermal Compensation
- Precision Enable and Power Good flag
- Programmable Soft-start
- 74-pin 12x14x4mm QFN package

#### **APPLICATIONS**

- Networking and Communications
- Fast Transient Point-of-Loads
- Industrial and Medical Equipment
- Embedded High Power FPGA

Ordering Information - back page

### **Typical Application**



# **Absolute Maximum Ratings**

Stresses beyond the limits listed below may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

PV <sub>IN</sub> , V <sub>IN</sub>	0.3V to 25V
V <sub>CC</sub>	0.3V to 6.0V
BST	0.3V to 31V <sup>1</sup>
BST-SW	0.3V to 6V
SW, ILIM	1V to 25V <sup>1, 2</sup>
ALL other pins	0.3V to VCC+0.3V
Storage Temperature	65°C to +150°C
Junction Temperature	150°C
Power Dissipation	Internally Limited
Lead Temperature (Soldering, 10 sec)	260°C MSL3
ESD Rating (HBM - Human Body Model)	2kV

# **Operating Conditions**

PV <sub>IN</sub> 3V to 22V
V <sub>IN</sub> 4.5V to 22V
V <sub>CC</sub> 4.5V to 5.5V
SW, ILIM1V to 22V <sup>1</sup>
PGOOD, $V_{CC}$ , $T_{ON}$ , SS, EN, FB0.3V to 5.5V
Switching Frequency400kHz to 600kHz <sup>3</sup>
Junction Temperature Range40°C to +125°C
JEDEC51 Package Thermal Resistance, $\theta_{\mbox{\scriptsize JA}}14.5^{\circ}\mbox{C/W}$
Package Power Dissipation at 25°C6.9W

Note 1: No external voltage applied.

Note 2: SW pin's minimum DC range is -1V, transient is -5V for less than 50ns.

Note 3: Recommended frequency for optimum performance

### **Electrical Characteristics**

Unless otherwise noted:  $T_J$ = 25°C,  $V_{IN}$ =12V, BST= $V_{CC}$ , SW=AGND=PGND=0V,  $C_{VCC}$ =4.7uF. Limits applying over the full operating temperature range are denoted by a " $\bullet$ "

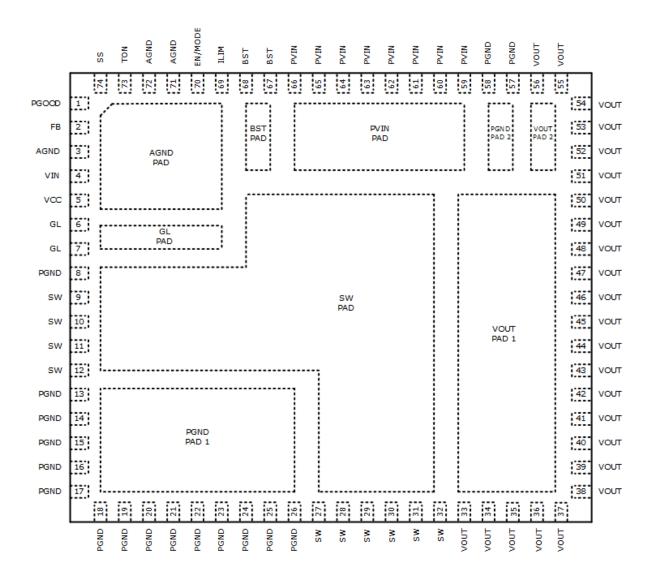
Symbol	Parameter	Conditions		Min	Тур	Max	Units		
Power Sup	Power Supply Characteristics								
V <sub>IN</sub>	Input Voltage Penge	VCC regulating	•	5		22	V		
VIN	Input Voltage Range	VCC tied to VIN	•	4.5		5.5	V		
I <sub>VIN</sub>	VIN Input Supply Current	Not switching, V <sub>IN</sub> = 12V, V <sub>FB</sub> = 0.7V	•		0.7	1.5	mA		
I <sub>VCC</sub>	VCC Quiescent Current	Not switching, V <sub>CC</sub> =V <sub>IN</sub> = 5V, V <sub>FB</sub> = 0.7V	•		0.7	1.5	mA		
I <sub>VIN</sub>	VIN Input Supply Current	f=500kHz, R <sub>ON</sub> =61.9k, VFB=0.58V			21		mA		
I <sub>OFF</sub>	Shutdown Current	Enable = 0V, V <sub>IN</sub> = 12V			1		μΑ		
Enable and	I Under-Voltage Lock-Out UVLO								
V <sub>IH_EN</sub>	EN Pin Rising Threshold		•	1.8	1.9	2.0	V		
V <sub>EN_HYS</sub>	EN Pin Hysteresis				50		mV		
V <sub>IH_EN</sub>	EN Pin Rising Threshold for DCM/ CCM operation		•	2.8	3.0	3.1	V		
V <sub>EN_HYS</sub>	EN Pin Hysteresis				100		mV		

Symbol	Parameter	Conditions		Min	Тур	Max	Units
	VCC UVLO Start Threshold, Rising Edge		•	4.00	4.25	4.40	V
	VCC UVLO Hysteresis				200		mV
Reference	Voltage						
		V <sub>IN</sub> = 5V to 22V, VCC regulating		0.597	0.600	0.603	V
.,		V <sub>IN</sub> = 4.5V to 5.5V, VCC tied to VIN		0.596	0.600	0.604	٧
$V_{REF}$	Reference Voltage	V <sub>IN</sub> = 5V to 22V, VCC regulating					
		V <sub>IN</sub> = 4.5V to 5.5V, VCC tied to VIN	•	0.594	0.600	0.606	V
	DC Line Regulation	CCM, closed loop, $V_{\rm IN}$ =4.5V-22V, applies to any $C_{\rm OUT}$			±0.17		%
	DC Load Regulation	CCM, closed loop, I <sub>OUT</sub> =0A-20A, applies to any C <sub>OUT</sub>			±0.12		%
Programma	able Constant On-Time						
T <sub>ON(MIN)</sub>	Minimum Programmable On-Time	R <sub>ON</sub> = 6.98k, V <sub>IN</sub> = 22V			125		ns
T <sub>ON2</sub>	On-Time 2	R <sub>ON</sub> = 6.98k, V <sub>IN</sub> = 12V	•	180	210	240	ns
	f Corresponding to On-Time 2	V <sub>OUT</sub> = 1.0V		430	490	575	kHz
T <sub>ON3</sub>	On-Time 3	R <sub>ON</sub> = 16.2k, V <sub>IN</sub> = 12V	•	375	445	515	ns
	Minimum Off-Time		•		250	350	ns
Diode Emu	lation Mode	1					
	Zero Crossing Threshold	DC value measured during test			-1		mV
Soft-start							
	SS Charge Current		•	-14	-10	-6	μΑ
	SS Discharge Current	Fault present	•	1			mA
VCC Linea	r Regulator						
	VCC Output Voltage	$V_{IN} = 6V$ to 22V, $I_{LOAD} = 0$ to 30mA	•	4.8	5.0	5.2	V
	voo output voltage	$V_{IN} = 5V$ , $I_{LOAD} = 0$ to 20mA	•	4.6	4.8		٧
Power Goo	od Output						
	Power Good Threshold			-10	-7.5	-5	%
	Power Good Hysteresis				2	4	%
	Power Good Sink Current			1			mA
Protection:	OCP, OTP, Short-Circuit						
	Hiccup Timeout				110		ms
	ILIM Pin Source Current			45	50	55	μΑ
	ILIM Current Temperature Coefficient				0.4		%/°C
	OCP Comparator Offset		•	-8	0	+8	mV

Symbol	Parameter	Conditions		Min	Тур	Max	Units
	Current Limit Blanking	GL rising>1V			100		ns
	Thermal Shutdown Threshold <sup>1</sup>	Rising temperature			150		°C
	Thermal Hysteresis <sup>1</sup>				15		°C
	VSCTH Feedback Pin Short-Circuit Threshold	Percent of V <sub>REF</sub> short circuit is active after PGOOD is asserted	•	50	60	70	%
Output Po	Output Power Stage						
	High-Side MOSFET R <sub>DSON</sub>				8.2	10	mΩ
R <sub>DSON</sub>	Low-Side MOSFET R <sub>DSON</sub>	I <sub>DS</sub> = 2A			2.8	3.3	mΩ
I <sub>OUT</sub>	Maximum Output Current		•	20			А
L	Output Inductance			0.45	0.56	0.67	uH
C <sub>IN</sub>	Input Capacitance				1		uF
C <sub>OUT</sub>	Output Capacitance				2.2		uF
C <sub>BST</sub>	Bootstrap Capacitance				0.1		uF

Note 1: Guaranteed by design

# **Pin Configuration, Top View**

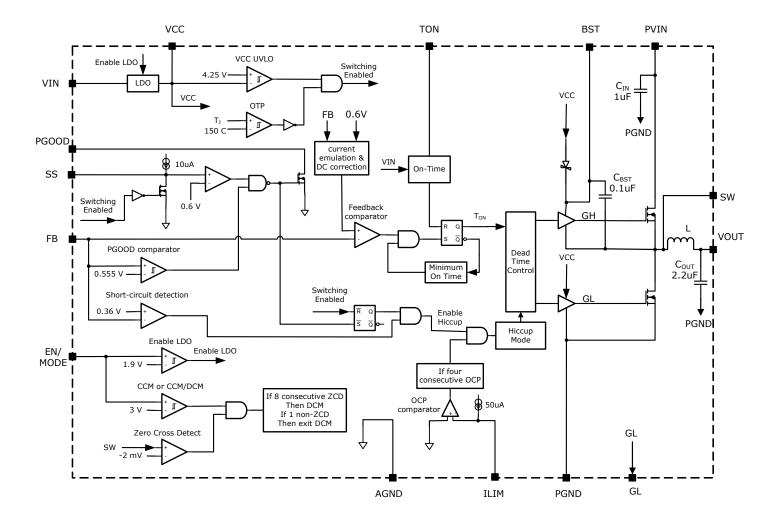


# **Pin Assignments**

Pin No.	Pin Name	Туре	Description	
1	PGOOD	OD, O	Power-good output. This open-drain output is pulled low when V <sub>OUT</sub> is outside the regulation.	
2	FB	A	Feedback input to feedback comparator. Connect with a set of resistors to VOUT and AGND in order to program VOUT.	
3, 71, 72, AGND PAD	AGND	А	Analog ground. Control circuitry of the IC is referenced to this pin. Should be connected to PVIN at a single point.	
4	VIN	PWR	Controller supply input. Provides power to internal LDO. Connect to PVIN.	
5	vcc	PWR	The output of LDO. Bypass with a 4.7uF capacitor to AGND. For operation from a $5V_{\text{IN}}$ rail, VCC should be tied to VIN.	
6, 7, GL PAD	GL	0	Driver output for Low-side N-channel synchronous MOSFET. It is internally connected to the gate of the MOSFET. Leave these pins floating.	
8	PGND	PWR	Controller low-side driver ground. Connect with a short trace to closest PGND pins or PGND pad.	
13-26, 57, 58, PGND PADS	PGND	PWR	Ground of the power stage. Should be connected to the system's power ground plane.	
9-12, 27-32, SW PAD	SW	PWR	Switching node. It is internally connected. Use thermal vias and/or sufficient PCB land area order to heatsink the low-side FET and the inductor.	
33-56, VOUT PADS	VOUT	PWR	Output of the power stage. Place the output filter capacitors as close as possible to these pins.	
59-66, PVIN PAD	PVIN	PWR	Power stage input voltage. Place the input filter capacitors as close as possible to these pins.	
67, 68, BST PAD	BST	A	Controller high-side driver supply pin. It is internally connected to SW via a 0.1uF bootstrap capacitor. Leave these pins floating.	
69	ILIM	Α	Over-current protection programming. Connect with a resistor to SW pins.	
70	EN/MODE	I	Precision enable pin. Pulling this pin above 1.9V will turn the Module on and it will operate in Forced CCM. If the voltage is raised above 3.0V, then the Module will operate in DCM or CCM depending on load.	
73	TON	А	Constant on-time programming pin. Connect with a resistor to AGND.	
74	SS	А	Soft-start pin. Connect an external capacitor between SS and AGND to program the soft-start rate based on the 10uA internal source current.	

Type: A = Analog, I = Input, O = Output, I/O = Input/Output, PWR = Power, OD = Open-Drain

# **Functional Block Diagram**



# **Typical Performance Characteristics**

Unless otherwise noted:  $V_{IN}$  = 12V,  $V_{OUT}$ =1.8V,  $I_{OUT}$ =20A, f=500kHz,  $T_A$  = 25°C. Schematic from the application information section.

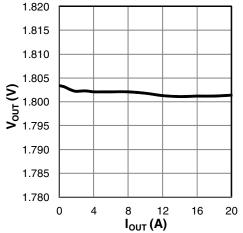


Figure 1: Load Regulation

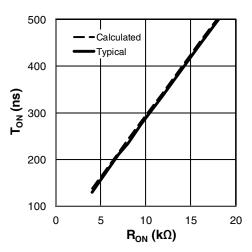


Figure 3: T<sub>ON</sub> versus R<sub>ON</sub>

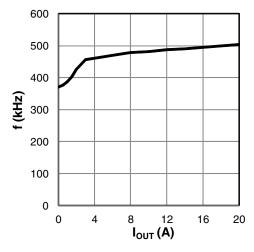


Figure 5: frequency versus I<sub>OUT</sub>

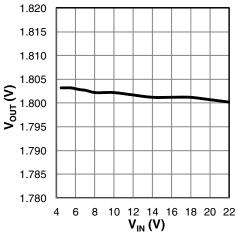


Figure 2: Line regulation

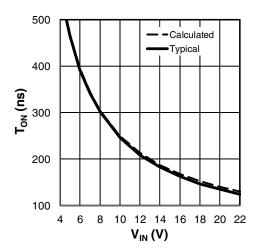


Figure 4: T<sub>ON</sub> versus V<sub>IN</sub>, R<sub>ON</sub>=6.98k

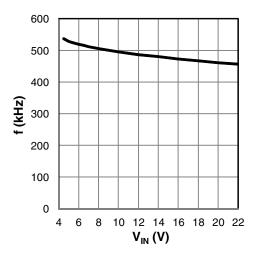


Figure 6: frequency versus V<sub>IN</sub>

# **Typical Performance Characteristics**

Unless otherwise noted:  $V_{IN}$  = 12V,  $V_{OUT}$ =1.8V,  $I_{OUT}$ =20A, f=500kHz,  $T_A$  = 25°C. Schematic from the application information section.

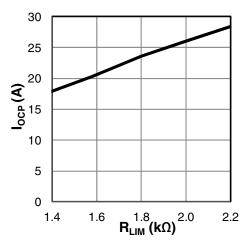


Figure 7: I<sub>OCP</sub> versus R<sub>LIM</sub>

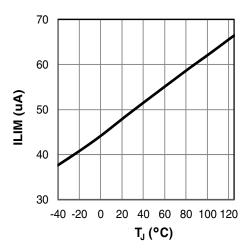


Figure 9: I<sub>LIM</sub> versus temperature

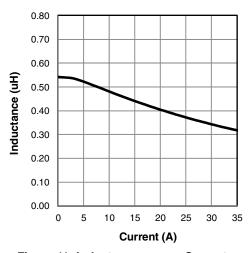


Figure 11: Inductance versus Current

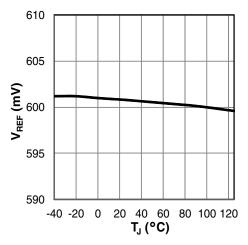


Figure 8: V<sub>REF</sub> versus temperature

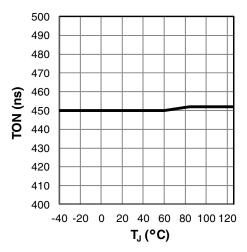


Figure 10:  $T_{ON}$  versus temperature,  $R_{ON}$ =16.2 $k\Omega$ 

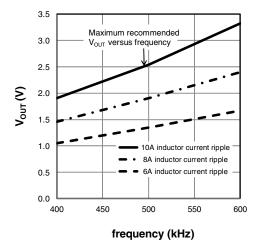


Figure 12:  $V_{OUT}$  versus f,  $V_{IN}$ =12V

# **Typical Performance Characteristics**

Unless otherwise noted:  $V_{IN}$  = 12V,  $V_{OUT}$ =1.8V,  $I_{OUT}$ =20A, f=500kHz,  $T_A$  = 25°C. Schematic from the application information section.

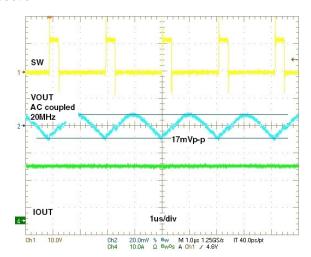


Figure 13: Steady state, I<sub>OUT</sub>=20A

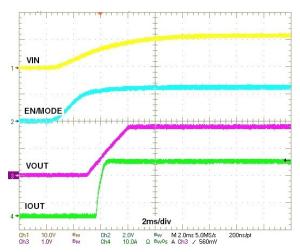


Figure 15: Power up, Forced CCM

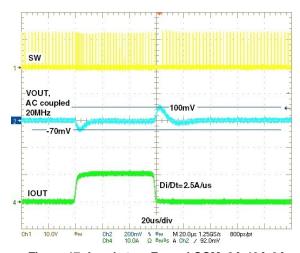


Figure 17: Load step, Forced CCM, 0A-10A-0A

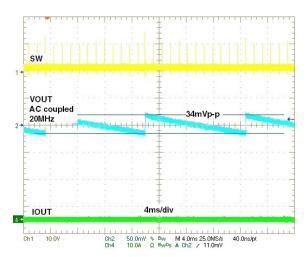


Figure 14: Steady state, DCM, I<sub>OUT</sub>=0A

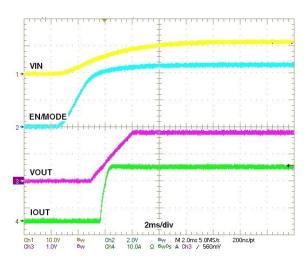


Figure 16: Power up, DCM/CCM

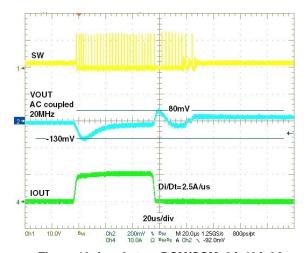


Figure 18: Load step, DCM/CCM, 0A-10A-0A

### **Efficiency and Package Thermal Derating**

Unless otherwise noted:  $T_{AMBIENT} = 25$ °C, No Air flow, f=500kHz, Schematic from the application information section.

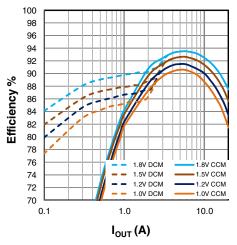


Figure 19: Efficiency, V<sub>IN</sub>=5V

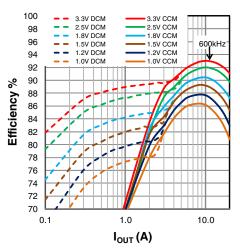


Figure 21: Efficiency, V<sub>IN</sub>=12V

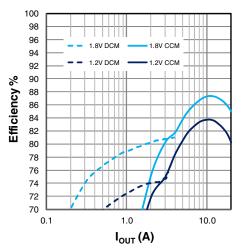


Figure 23: Efficiency, V<sub>IN</sub>=19.6V

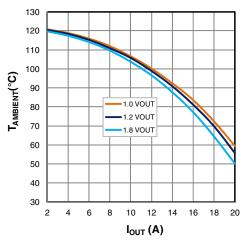


Figure 20: Maximum  $T_{AMBIENT}$  vs  $I_{OUT}$ ,  $V_{IN}$ =5V

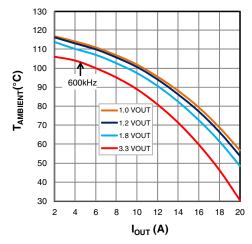


Figure 22: Maximum  $T_{AMBIENT}$  vs  $I_{OUT}$ ,  $V_{IN}$ =12V

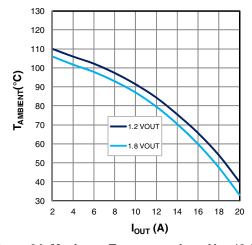


Figure 24: Maximum  $T_{AMBIENT}$  vs  $I_{OUT}$ ,  $V_{IN}$ =19.6V

### **Functional Description**

XR79120 is a synchronous step-down proprietary emulated current-mode Constant On-Time (COT) Module. The ontime, which is programmed via  $R_{ON},$  is inversely proportional to  $V_{IN}$  and maintains a nearly constant frequency. The emulated current-mode control is stable with ceramic output capacitors.

Each switching cycle begins with GH signal turning on the high-side (switching) FET for a preprogrammed time. At the end of the on-time, the high-side FET is turned off and the low-side (synchronous) FET is turned on for a preset minimum time (250ns nominal). This parameter is termed Minimum Off-Time. After the minimum off-time, the voltage at the feedback pin FB is compared to an internal voltage ramp at the feedback comparator. When  $V_{FB}$  drops below the ramp voltage, the high-side FET is turned on and the cycle repeats. This voltage ramp constitutes an emulated current ramp and makes possible the use of ceramic capacitors, in addition to other capacitor types, for output filtering.

### **Enable/Mode Input (EN/MODE)**

EN/MODE pin accepts a tri-level signal that is used to control turn on/off. It also selects between two modes of operation: 'Forced CCM' and 'DCM/CCM'. If EN is pulled below 1.8V, the Module shuts down. A voltage between 2.0V and 2.8V selects the Forced CCM mode which will run the Module in continuous conduction at all times. A voltage higher than 3.1V selects the DCM/CCM mode which will run the Module in discontinuous conduction at light loads.

#### **Selecting the Forced CCM Mode**

In order to set the Module to operate in Forced CCM, a voltage between 2.0V and 2.8V must be applied to EN/MODE. This can be achieved with an external control signal that meets the above voltage requirement. Where an external control is not available, the EN/MODE can be derived from  $V_{IN}.$  If  $V_{IN}$  is well regulated, use a resistor divider and set the voltage to 2.5V. If  $V_{IN}$  varies over a wide range, the circuit shown in figure 25 can be used to generate the required voltage. Note that at  $V_{IN}$  of 4.5V and 22V the nominal Zever voltage is 3.8V and 4.7V respectively. Therefore for  $V_{IN}$  in the range of 4.5V to 22V, the circuit shown in figure 25 will generate  $V_{EN}$  required for Forced CCM.

#### Selecting the DCM/CCM Mode

In order to set the Module operation to DCM/CCM, a voltage between 3.1V and 5.5V must be applied to EN/MODE pin. If an external control signal is available, it can be directly connected to EN/MODE. In applications where an external control is not available, EN/MODE input can be derived from  $V_{\rm IN}$ . If  $V_{\rm IN}$  is well regulated, use a resistor

divider and set the voltage to 4V. If  $V_{\rm IN}$  varies over a wide range, the circuit shown in figure 26 can be used to generate the required voltage.

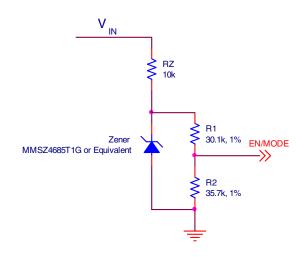


Figure 25: Selecting Forced CCM by deriving EN/MODE from  $V_{\rm IN}$ 

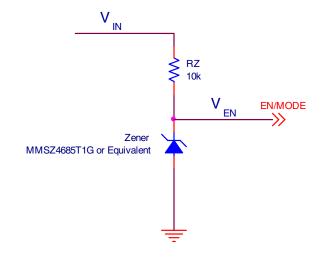


Figure 26: Selecting DCM/CCM by deriving EN/MODE from  $\rm V_{IN}$ 

#### **Programming the On-Time**

The On-Time  $T_{ON}$  is programmed via resistor  $R_{ON}$  according to following equation:

$$R_{ON} = \frac{V_{IN} \times [T_{ON} - (30 \times 10^{-9})]}{3.1 \times 10^{-10}}$$

where T<sub>ON</sub> is calculated from:

$$T_{ON} = \frac{V_{OUT}}{V_{IN} \times f \times Eff}$$

where:

f is the desired switching frequency at nominal  $I_{OUT}$ 

Eff is the Module efficiency corresponding to nominal  $I_{OUT}$  shown in figures 19, 21, 23

Substituting for T<sub>ON</sub> in the first equation we get:

$$R_{ON} = \frac{\left(\frac{V_{OUT}}{f \times Eff}\right) - [(30 \times 10^{-9}) \times V_{IN}]}{3.1 \times 10^{-10}}$$

#### **Over-Current Protection (OCP)**

If load current exceeds the programmed over-current,  $I_{OCP}$  for four consecutive switching cycles, then Module enters hiccup mode of operation. In hiccup, the MOSFET gates are turned off for 110ms (hiccup timeout). Following the hiccup timeout, a soft-start is attempted. If OCP persists, hiccup timeout will repeat. The Module will remain in hiccup mode until load current is reduced below the programmed  $I_{OCP}$ . In order to program the over-current protection, use the following equation:

$$RLIM = \frac{(I_{OCP} \times RDS) + 8mV}{ILIM}$$

Where:

RLIM is resistor value for programming I<sub>OCP</sub>

I<sub>OCP</sub> is the over-current threshold to be programmed

RDS is the MOSFET rated On Resistance  $(3.3 \text{m}\Omega)$ 

8mV is the OCP comparator maximum offset

ILIM is the internal current that generates the necessary OCP comparator threshold (use 45µA).

Note that ILIM has a positive temperature coefficient of 0.4%/°C (figure 9). This is meant to roughly match and compensate for positive temperature coefficient of the synchronous FET. Graph of typical  $I_{OCP}$  versus RLIM is shown in figure 7.

#### **Short-Circuit Protection (SCP)**

If the output voltage drops below 60% of its programmed value, the Module will enter hiccup mode. Hiccup will persist until short-circuit is removed. SCP circuit becomes active after PGOOD asserts high.

### **Over-Temperature (OTP)**

OTP triggers at a nominal die temperature of 150°C. The gate of switching FET and synchronous FET are turned off. When die temperature cools down to 135°C, soft-start is initiated and operation resumes.

### **Programming the Output Voltage**

Use an external voltage divider as shown in the Application Circuit to program the output voltage  $V_{\text{OUT}}$ .

$$R1 = R2 \times \left(\frac{V_{OUT}}{0.6} - 1\right)$$

where R2 has a nominal value of  $2k\Omega$ .

#### **Programming the Soft-start**

Place a capacitor CSS between the SS and AGND pins to program the soft-start. In order to program a soft-start time of TSS, calculate the required capacitance CSS from the following equation:

$$CSS = TSS \times \left(\frac{10\mu A}{0.6V}\right)$$

### Feed-Forward Capacitor (C<sub>FF</sub>)

A feed-forward capacitor ( $C_{FF}$ ) may be necessary depending on the Equivalent Series Resistance (ESR) of  $C_{OUT}$ . If only ceramic output capacitors are used for  $C_{OUT}$  then a  $C_{FF}$  is necessary. Calculate  $C_{FF}$  from:

$$C_{FF} = \frac{1}{2 \times \pi \times R1 \times 7 \times f_{LC}}$$

 $\Delta$ IL for V<sub>IN</sub>=12V. As an example, for operating conditions of V<sub>IN</sub>=12V, V<sub>OUT</sub>=1.5V and f=500kHz the current ripple is about 6.5A. Note that maximum recommended peak-to-peak  $\Delta$ IL is 10A. Therefore the maximum permissible V<sub>OUT</sub> versus f corresponds to the top curve in figure 12. For example with V<sub>IN</sub>=12V and f=500kHz maximum V<sub>OUT</sub> is 2.5V.

where:

R1 is the resistor that CFF is placed in parallel with

f<sub>LC</sub> is the frequency of output filter double-pole

 $f_{LC}$  must be less than 13kHz when using ceramic  $C_{OUT}$ . If necessary, increase  $C_{OUT}$  in order to meet this constraint.

When using capacitors with higher ESR, such as PANA-SONIC TPE series, a C<sub>FF</sub> is not required provided following conditions are met:

- 1. The frequency of output filter LC double-pole  $f_{\text{LC}}$  should be less than 10kHz.
- 2. The frequency of ESR Zero  $f_{\mbox{\scriptsize Zero},\mbox{\scriptsize ESR}}$  should be at least five times larger than  $f_{\mbox{\scriptsize LC}}.$

Note that if  $f_{Zero,ESR}$  is less than  $5xf_{LC}$ , then it is recommended to set the  $f_{LC}$  at less than 2kHz. CFF is still not required.

### Maximum Allowable Voltage Ripple at FB pin

Note that the steady-state voltage ripple at feedback pin FB ( $V_{FB,RIPPLE}$ ) must not exceed 50mV in order for the Module to function correctly. If  $V_{FB,RIPPLE}$  is larger than 50mV then  $C_{OUT}$  should be increased as necessary in order to keep the  $V_{FB,RIPPLE}$  below 50mV.

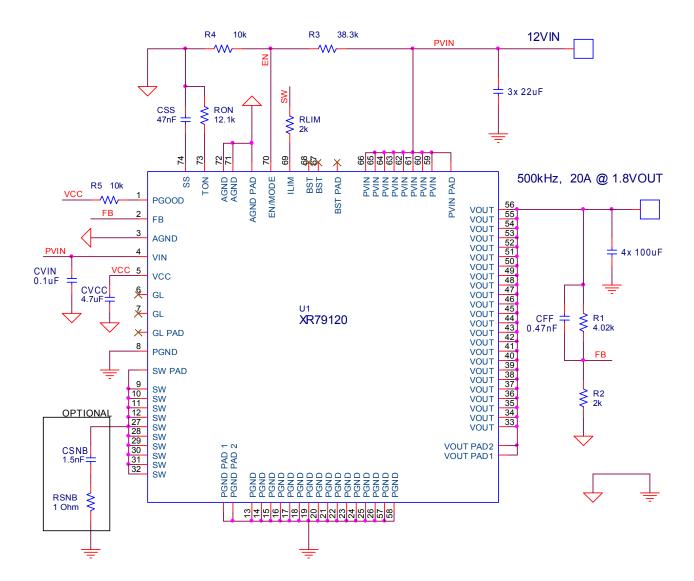
#### Feed-Forward Resistor (RFF)

Poor PCB layout can cause FET switching noise at the output and may couple to the FB pin via  $C_{FF.}$  Excessive noise at FB will cause poor load regulation. To solve this problem place a resistor  $R_{FF}$  in series with  $C_{FF.}$   $R_{FF.}$  value up to 2% of R1 is acceptable.

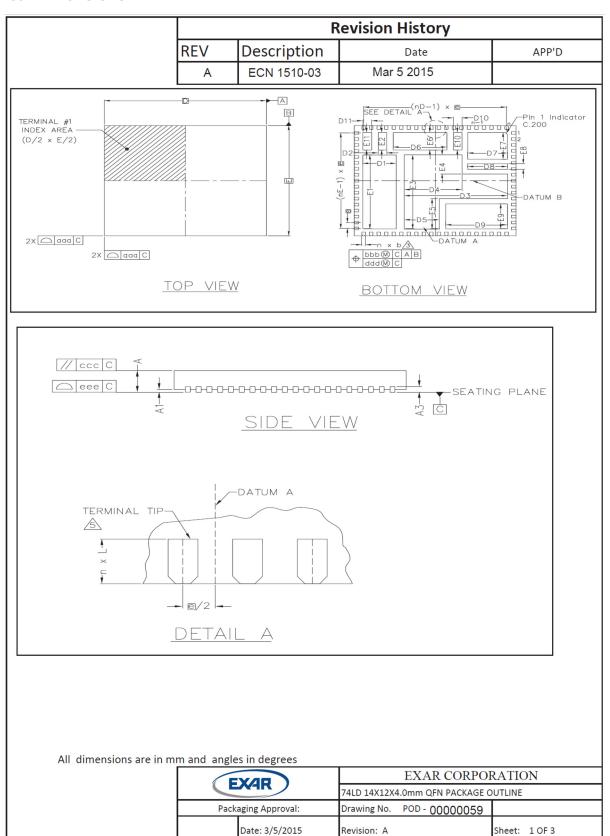
#### Maximum recommended V<sub>OUT</sub> versus frequency

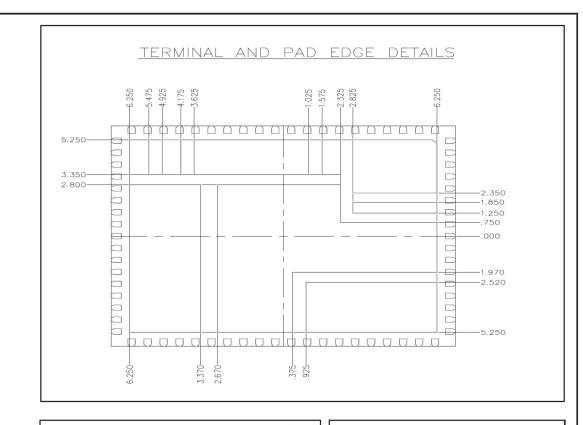
 $V_{OUT}$  versus frequency curves corresponding to inductor current ripple  $\Delta IL$  of 10A, 8A and 6A are plotted in figure 12. These curves show the relationship between  $V_{OUT}$ , f and

# **Application Circuit**



### **Mechanical Dimensions**



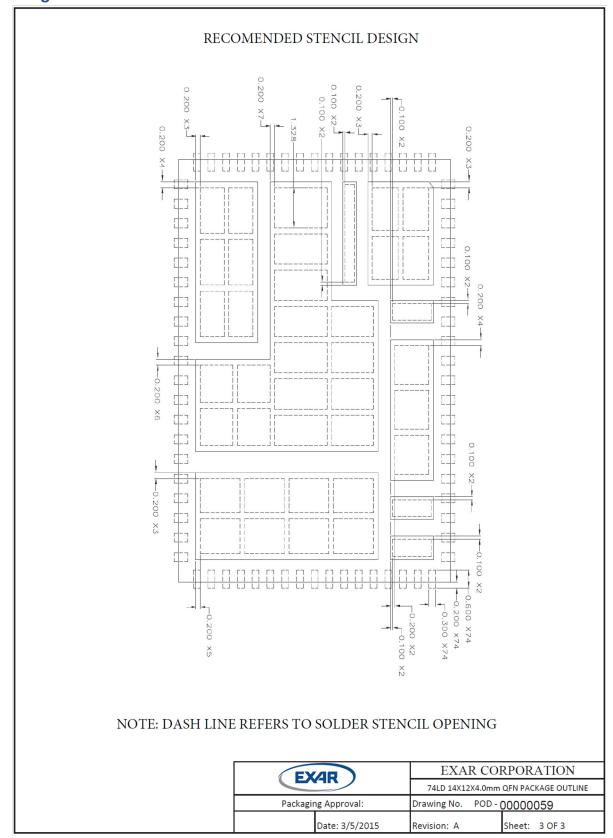


PACKAGE	74L 14×12×4mm QFN			
REF.	MIN.	NOM.	MAX.	
Α	3.90	4.00	4.10	
b	0.25	0.30	0.35	
L	0.30	0.40	0.50	
D		14.00 BSC		
D1	2.78	2.88	2.98	
D2	0.65	0.75	0.85	
D3	8.82	8.92	9.02	
D4	4.895	4.995	5.005	
D5	2.945	3.045	3.145	
D6	4.55	4.65	4.75	
D7	3.325	3.425	3.525	
D8	3.325	3.425	3.525	
D9	5.225	5.325	5.425	
D10	0.65	0.75	0.85	
D11	0.675	0.775	0.875	
E		12.00 BSC		
E1	7.95	8.05	8.15	
E2	1.80	1.90	2.00	
E3	7.95	8.05	8.15	
E4	1.95	2.05	2.15	
E5	3.18	3.28	3.38	
E6	1.80	1.90	2.00	
E7	2.80	2.90	3.00	
E8	0.50	0.60	0.70	
E9	2.63	2.73	2.83	
E10	1.80	1.90	2.00	
E11	1.80	1.90	2.00	
е		0.65 BSC		
n		74		
nD		20		
nE		17		

SYMBO.	СОММО	N DIME	NSIONS	N O T		
L	MIN.	NOM.	MAX.	E		
Α1	0	0 0.02 0.05				
АЗ		0.20 REF.				
TOL	ERANCES	OF FORM A	AND POSITI	ON		
aaa		0.10				
bbb		0.10				
ccc		0.10				
ddd		0.05				
eee		0.08				

EXAR	EXAR CORPORATION				
DVAK	74LD 14X12X4.0mm QFN PACKAGE OUTLINE				
Packaging Approval:	Drawing No. POD - 00000059				
Date: 3/5/2015	Revision: A	Sheet: 2 OF 3			

# **Stencil Design**



### **Ordering Information**

Part Number	Package	JEDEC Compliant	Operating Temperature Range	Packaging Quantity	Marking	
XR79120EL-F	10::14:mm OFN	V	4000 + 40500	Tray	XR79120EL	
XR79120ELTR-F	12x14mm QFN	Yes	-40°C to +125°C	Tape and Reel	YYWWF XXXXXXXX	
XR79120EVB	XR79120 Ev	aluation Board				

<sup>&</sup>quot;YY" = Year (last two digits)- "WW" = Work Week- "X" = Lot Number; when applicable

### **Revision History**

Revision	Date	Description
1A	March 2015	ECN 1512-02

#### For Further Assistance:

Technical Support: techsupport.exar.com

Technical Documentation: www.exar.com/techdoc

 Exar Corporation Headquarters and Sales Offices

 48720 Kato Road
 Tel.: +1 (510) 668-7000

 Fremont, CA 95438 - USA
 Fax: +1 (510) 668-7001



#### NOTICE

EXAR Corporation reserves the right to make changes to the products contained in this publication in order to improve design, performance or reliability. EXAR Corporation assumes no responsibility for the use of any circuits described herein, conveys no license under any patent or other right, and makes no representation that the circuits are free of patent infringement. Charts and schedules contained herein are only for illustration purposes and may vary depending upon a user's specific application. While the information in this publication has been carefully checked; no responsibility, however, is assumed for inaccuracies.

EXAR Corporation does not recommend the use of any of its products in life support applications where the failure or malfunction of the product can reasonably be expected to cause failure of the life support system or to significantly affect its safety or effectiveness. Products are not authorized for use in such applications unless EXAR Corporation receives, in writing, assurances to its satisfaction that: (a) the risk of injury or damage has been minimized; (b) the user assumes all such risks; (c) potential liability of EXAR Corporation is adequately protected under the circumstances.

Reproduction, in part or whole, without the prior written consent of EXAR Corporation is prohibited.

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

# Exar:

XR79120EVB XR79120EL-F